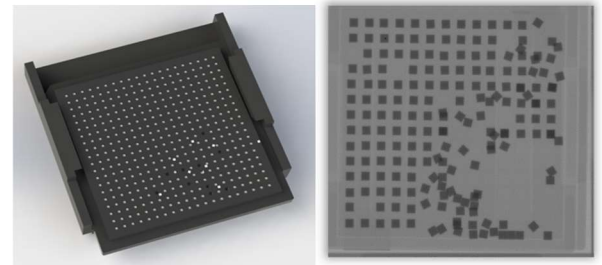


LID/CLIP SUPER SYSTEM (LCS2™)

Preliminary Product Datasheet

Shipping today's thin die (<250µm) in industry standard waffle packs presents a challenge for many semiconductor manufacturers. Thin devices packaged in these chip trays have a tendency to migrate causing costly Component-Out-Of-Pocket (COOP) damage to occur.



Die Migrated out of Waffle Pack

X-Ray Image of Migrated Die

Developed in partnership BAE Systems, Gel-Pak's patented LCS2 Lid/Clip Super System prevents thin semiconductor die from migrating out of waffle pack/chip tray pockets during shipping and handling. The lid is designed to work with a new highly engineered clip that uniformly compresses the tray and lid together.

LCS2 Features and Benefits

- "Gold" colored ESD Class 000 static dissipative molded clip and lid (SR < E9 ohms)
- Integrated interleaf material options: Industry standard anti-static Tyvek paper or ultra-pure static dissipative black polystyrene
- Eliminates the manual placement and misalignment and/or pinching of Tyvek paper when loading waffle pack
- Silicone-free
- Uniformly seals each individual tray pocket
- Compensates for common waffle pack lid/tray warpage conditions that create gaps that enable die migration
- Saves significant costs associated with yield loss, rework labor and RMAs caused by die migration issue

